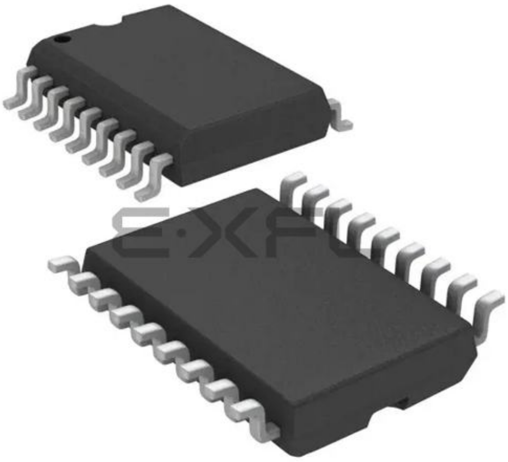
Microchip Technology - PIC16LF628A-I/SO Datasheet



What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	16
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	224 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf628a-i-so

PIC16F62X

FLASH-Based 8-Bit CMOS Microcontrollers

Devices Included in this Data Sheet:

- PIC16F627
- PIC16F628

Referred to collectively as PIC16F62X

High Performance RISC CPU:

- Only 35 instructions to learn
- All single cycle instructions (200 ns), except for program branches which are two-cycle
- Operating speed:
  - DC - 20 MHz clock input
  - DC - 200 ns instruction cycle

Device	Memory		
	FLASH Program	RAM Data	EEPROM Data
PIC16F627	1024 x 14	224 x 8	128 x 8
PIC16F628	2048 x 14	224 x 8	128 x 8

- Interrupt capability
- 16 special function hardware registers
- 8-level deep hardware stack
- Direct, Indirect and Relative addressing modes

Peripheral Features:

- 16 I/O pins with individual direction control
- High current sink/source for direct LED drive
- Analog comparator module with:
  - Two analog comparators
  - Programmable on-chip voltage reference (V_{REF}) module
  - Programmable input multiplexing from device inputs and internal voltage reference
  - Comparator outputs are externally accessible
- Timer0: 8-bit timer/counter with 8-bit programmable prescaler
- Timer1: 16-bit timer/counter with external crystal/clock capability
- Timer2: 8-bit timer/counter with 8-bit period register, prescaler and postscaler
- Capture, Compare, PWM (CCP) module
  - Capture is 16-bit, max. resolution is 12.5 ns
  - Compare is 16-bit, max. resolution is 200 ns
  - PWM max. resolution is 10-bit
- Universal Synchronous/Asynchronous Receiver/Transmitter USART/SCI
- 16 Bytes of common RAM

Special Microcontroller Features:

- Power-on Reset (POR)
- Power-up Timer (PWRT) and Oscillator Start-up Timer (OST)
- Brown-out Detect (BOD)
- Watchdog Timer (WDT) with its own on-chip RC oscillator for reliable operation
- Multiplexed $\overline{\text{MCLR}}$-pin
- Programmable weak pull-ups on PORTB
- Programmable code protection
- Low voltage programming
- Power saving SLEEP mode
- Selectable oscillator options
  - FLASH configuration bits for oscillator options
  - ER (External Resistor) oscillator
    - Reduced part count
  - Dual speed INTRC
    - Lower current consumption
  - EC External Clock input
  - XT Oscillator mode
  - HS Oscillator mode
  - LP Oscillator mode
- In-circuit Serial Programming™ (via two pins)
- Four user programmable ID locations

CMOS Technology:

- Low power, high speed CMOS FLASH technology
- Fully static design
- Wide operating voltage range
  - PIC16F627 - 3.0V to 5.5V
  - PIC16F628 - 3.0V to 5.5V
  - PIC16LF627 - 2.0V to 5.5V
  - PIC16LF628 - 2.0V to 5.5V
- Commercial, industrial and extended temperature range
- Low power consumption
  - < 2.0 mA @ 5.0V, 4.0 MHz
  - 15 μA typical @ 3.0V, 32 kHz
  - < 1.0 μA typical standby current @ 3.0V

NOTES:

1.0 PIC16F62X DEVICE VARIETIES

A variety of frequency ranges and packaging options are available. Depending on application and production requirements, the proper device option can be selected using the information in the PIC16F62X Product Identification System section (Page 167) at the end of this data sheet. When placing orders, please use this page of the data sheet to specify the correct part number.

1.1 FLASH Devices

FLASH devices can be erased and reprogrammed electrically. This allows the same device to be used for prototype development, pilot programs and production.

A further advantage of the electrically-erasable FLASH is that it can be erased and reprogrammed in-circuit, or by device programmers, such as Microchip's PICSTART® Plus, or PRO MATE® II programmers.

1.2 Quick-Turnaround Production (QTP) Devices

Microchip offers a QTP Programming Service for factory production orders. This service is made available for users who chose not to program a medium-to-high quantity of units and whose code patterns have stabilized. The devices are standard FLASH devices but with all program locations and configuration options already programmed by the factory. Certain code and prototype verification procedures apply before production shipments are available. Please contact your Microchip Technology sales office for more details.

1.3 Serialized Quick-Turnaround Production (SQTP^{sm}) Devices

Microchip offers a unique programming service where a few user-defined locations in each device are programmed with different serial numbers. The serial numbers may be random, pseudo-random or sequential.

Serial programming allows each device to have a unique number which can serve as an entry-code, password or ID number.

3.2.2.3 INTCON Register

The INTCON register is a readable and writable register which contains the various enable and flag bits for all interrupt sources except the comparator module. See Section 3.2.2.4 and Section 3.2.2.5 for a description of the comparator enable and flag bits.

Note:	Interrupt flag bits get set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>).

REGISTER 3-3: INTCON REGISTER (ADDRESS: 0Bh, 8Bh, 10Bh, 18Bh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x
GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF
bit 7							bit 0

bit 7 **GIE:** Global Interrupt Enable bit
`1` = Enables all unmasked interrupts
`0` = Disables all interrupts

bit 6 **PEIE**: Peripheral Interrupt Enable bit
`1` = Enables all unmasked peripheral interrupts
`0` = Disables all peripheral interrupts

bit 5 **T0IE**: TMR0 Overflow Interrupt Enable bit
`1` = Enables the TMR0 interrupt
`0` = Disables the TMR0 interrupt

bit 4 **INTE**: RB0/INT External Interrupt Enable bit
`1` = Enables the RB0/INT external interrupt
`0` = Disables the RB0/INT external interrupt

bit 3 **RBIE**: RB Port Change Interrupt Enable bit
`1` = Enables the RB port change interrupt
`0` = Disables the RB port change interrupt

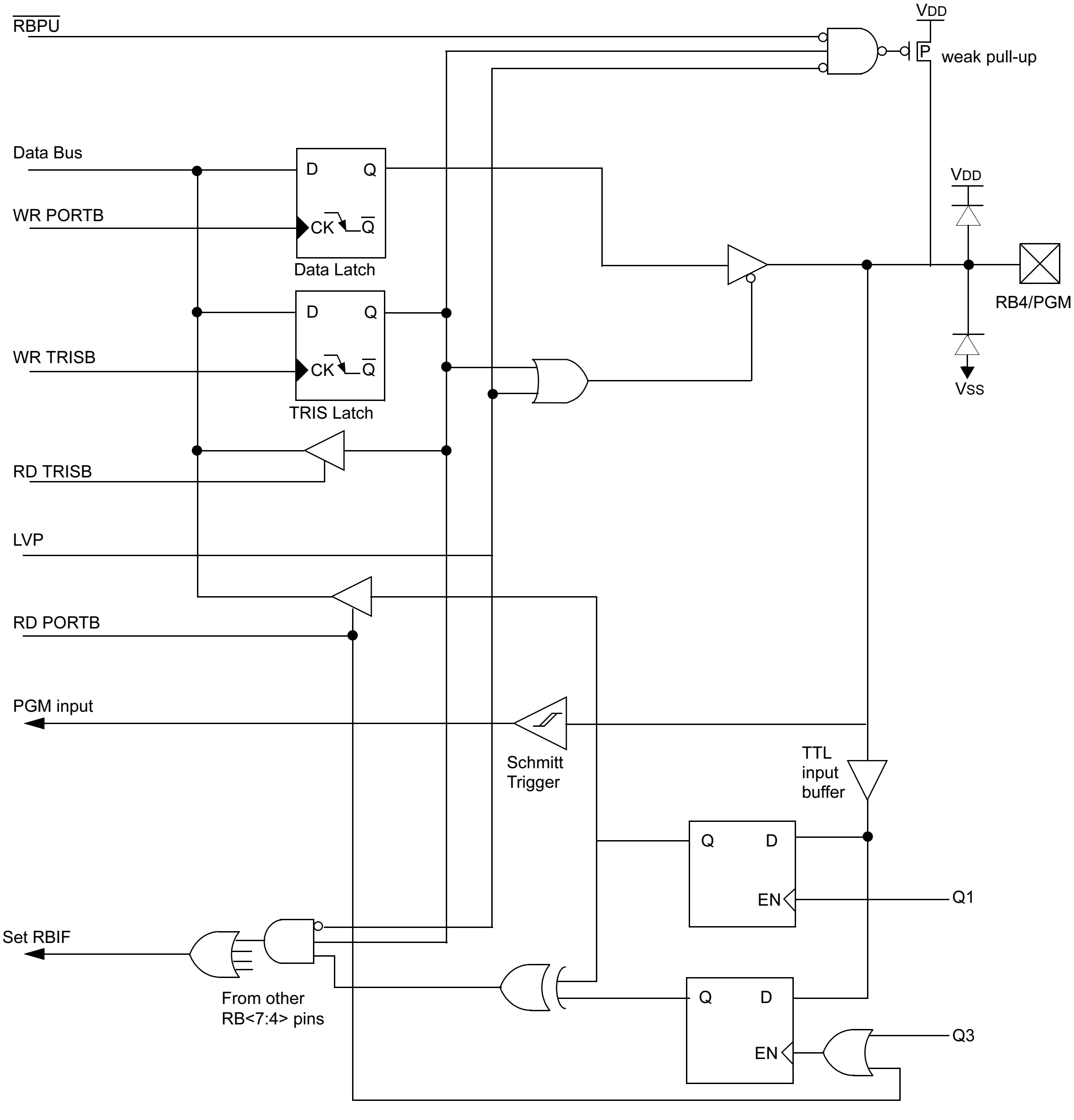
bit 2 **T0IF**: TMR0 Overflow Interrupt Flag bit
`1` = TMR0 register has overflowed (must be cleared in software)
`0` = TMR0 register did not overflow

bit 1 **INTF**: RB0/INT External Interrupt Flag bit
`1` = The RB0/INT external interrupt occurred (must be cleared in software)
`0` = The RB0/INT external interrupt did not occur

bit 0 **RBIF**: RB Port Change Interrupt Flag bit
`1` = When at least one of the RB7:RB4 pins changed state (must be cleared in software)
`0` = None of the RB7:RB4 pins have changed state

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

FIGURE 5-12: BLOCK DIAGRAM OF RB4/PGM PIN



Note 1: The low voltage programming disables the interrupt-on-change and the weak pull-ups on RB4.

5.3 I/O Programming Considerations

5.3.1 BI-DIRECTIONAL I/O PORTS

Any instruction which writes, operates internally as a read followed by a write operation. The `BCF` and `BSF` instructions, for example, read the register into the CPU, execute the bit operation and write the result back to the register. Caution must be used when these instructions are applied to a port with both inputs and outputs defined. For example, a `BSF` operation on Bit 5 of PORTB will cause all eight bits of PORTB to be read into the CPU. Then the `BSF` operation takes place on Bit 5 and PORTB is written to the output latches. If another bit of PORTB is used as a bi-directional I/O pin (e.g., Bit 0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and rewritten to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the Input mode, no problem occurs. However, if Bit 0 is switched into Output mode later on, the content of the data latch may now be unknown.

Reading a port register, reads the values of the port pins. Writing to the port register writes the value to the port latch. When using read-modify-write instructions (ex. `BCF, BSF`, etc.) on a port, the value of the port pins is read, the desired operation is done to this value, and this value is then written to the port latch.

Example 5-2 shows the effect of two sequential read-modify-write instructions (ex., `BCF, BSF`, etc.) on an I/O port.

A pin actively outputting a Low or High should not be driven from external devices at the same time in order to change the level on this pin (“wired-or”, “wired-and”). The resulting high output currents may damage the chip.

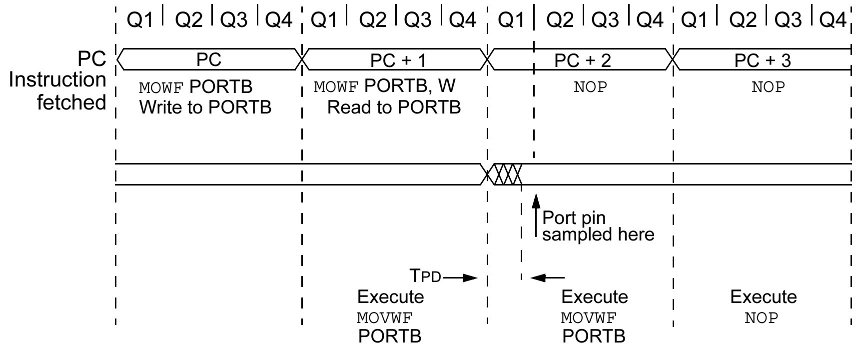
EXAMPLE 5-2: READ-MODIFY-WRITE INSTRUCTIONS ON AN I/O PORT

```
;Initial PORT settings:PORTB<7:4> Inputs
;
;                      PORTB<3:0> Outputs
;PORTB<7:6> have external pull-up and are not
;connected to other circuitry
;
;                      PORT latchPORT Pins
;                      ---------- ----------
    BCF STATUS, RP0   ;
    BCF PORTB, 7      ;01pp pppp 11pp pppp
    BSF STATUS, RP0   ;
    BCF TRISB, 7      ;10pp pppp 11pp pppp
    BCF TRISB, 6      ;10pp pppp 10pp pppp
;
;Note that the user may have expected the pin
;values to be 00pp pppp. The 2nd BCF caused
;RB7 to be latched as the pin value (High).
```

5.3.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 5-16). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should be such to allow the pin voltage to stabilize (load dependent) before the next instruction which causes that file to be read into the CPU is executed. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with a `NOP` or another instruction not accessing this I/O port.

FIGURE 5-16: SUCCESSIVE I/O OPERATION



Note 1: This example shows write to PORTB followed by a read from PORTB.

2: Data setup time = (0.25 TCY - TPD) where TCY = instruction cycle and TPD = propagation delay of Q1 cycle to output valid. Therefore, at higher clock frequencies, a write followed by a read may be problematic.

10.0 VOLTAGE REFERENCE MODULE

The Voltage Reference is a 16-tap resistor ladder network that provides a selectable voltage reference. The resistor ladder is segmented to provide two ranges of VREF values and has a power-down function to conserve power when the reference is not being used. The VRCON register controls the operation of the reference as shown in Figure 10-1. The block diagram is given in Figure 10-1.

10.1 Configuring the Voltage Reference

The Voltage Reference can output 16 distinct voltage levels for each range.

The equations used to calculate the output of the Voltage Reference are as follows:

if VRR = 1: VREF = (VR<3:0>/24) x VDD

if VRR = 0: VREF = (VDD x 1/4) + (VR<3:0>/32) x VDD

The setting time of the Voltage Reference must be considered when changing the VREF output (Table 17-2). Example 10-1 shows an example of how to configure the Voltage Reference for an output voltage of 1.25V with VDD = 5.0V.

REGISTER 10-1: VRCON REGISTER (ADDRESS: 9Fh)

R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
VREN	VROE	VRR	—	VR3	VR2	VR1	VR0
bit 7							bit 0

bit 7 **VREN:** VREF Enable
`1` = VREF circuit powered on
`0` = VREF circuit powered down, no IDD drain

bit 6 **VROE:** VREF Output Enable
`1` = VREF is output on RA2 pin
`0` = VREF is disconnected from RA2 pin

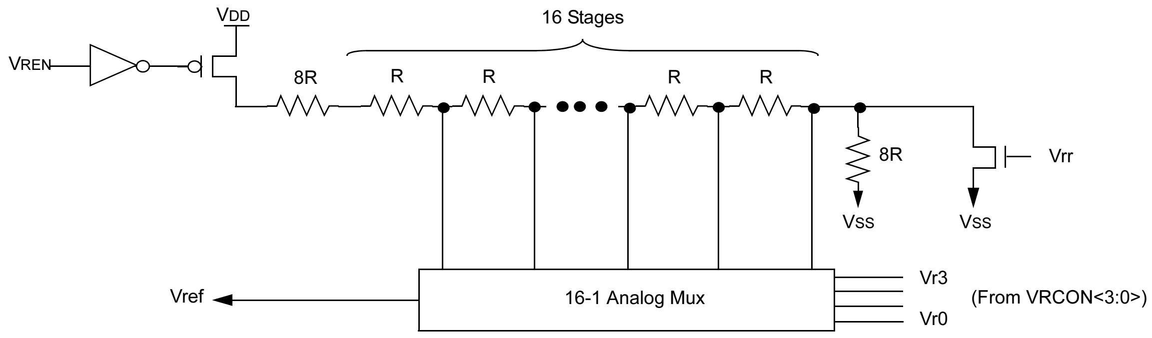
bit 5 **VRR:** VREF Range selection
`1` = Low Range
`0` = High Range

bit 4 **Unimplemented:** Read as '0'

bit 3-0 **VR<3:0>**: VREF value selection 0 ≤ VR [3:0] ≤ 15
When VRR = 1: VREF = (VR<3:0>/ 24) * VDD
When VRR = 0: VREF = 1/4 * VDD + (VR<3:0>/ 32) * VDD

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

FIGURE 10-1: VOLTAGE REFERENCE BLOCK DIAGRAM



Note 1: R is defined in Table 17-2.

12.0 UNIVERSAL SYNCHRONOUS/ ASYNCHRONOUS RECEIVER/ TRANSMITTER (USART) MODULE

The Universal Synchronous Asynchronous Receiver Transmitter (USART) module is one of the two serial I/O modules. (USART is also known as a Serial Communications Interface or SCI). The USART can be configured as a full duplex asynchronous system that can communicate with peripheral devices such as CRT terminals and personal computers, or it can be configured as a half duplex synchronous system that can communicate with peripheral devices such as A/D or D/A integrated circuits, Serial EEPROMs etc.

The USART can be configured in the following modes:

- Asynchronous (full duplex)
- Synchronous - Master (half duplex)
- Synchronous - Slave (half duplex)

Bit SPEN (RCSTA<7>), and bits TRISB<2:1>, have to be set in order to configure pins RB2/TX/CK and RB1/RX/DT as the Universal Synchronous Asynchronous Receiver Transmitter.

REGISTER 12-1: TXSTA: TRANSMIT STATUS AND CONTROL REGISTER (ADDRESS: 98h)

R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R-1	R/W-0
CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D
bit 7							bit 0

bit 7	**CSRC**: Clock Source Select bit Asynchronous mode Don’t care Synchronous mode `1` = Master mode (Clock generated internally from BRG) `0` = Slave mode (Clock from external source)
bit 6	**TX9**: 9-bit Transmit Enable bit `1` = Selects 9-bit transmission `0` = Selects 8-bit transmission
bit 5	**TXEN**: Transmit Enable bit(1) `1` = Transmit enabled `0` = Transmit disabled
bit 4	**SYNC**: USART Mode Select bit `1` = Synchronous mode `0` = Asynchronous mode
bit 3	**Unimplemented:** Read as '0'
bit 2	**BRGH**: High Baud Rate Select bit Asynchronous mode `1` = High speed `0` = Low speed Synchronous mode Unused in this mode
bit 1	**TRMT**: Transmit Shift Register STATUS bit `1` = TSR empty `0` = TSR full
bit 0	**TX9D**: 9th bit of transmit data. Can be PARITY bit.

Note 1: SREN/CREN overrides TXEN in SYNC mode.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

TABLE 12-4: BAUD RATES FOR ASYNCHRONOUS MODE (BRGH = 0)

BAUD RATE (K)	Fosc = 20 MHz		SPBRG value (decimal)	16 MHz		SPBRG value (decimal)	10 MHz		SPBRG value (decimal)
	KBAUD	ERROR		KBAUD	ERROR		KBAUD	ERROR	
0.3	NA	—	—	NA	—	—	NA	—	—
1.2	1.221	+1.73%	255	1.202	+0.16%	207	1.202	+0.16%	129
2.4	2.404	+0.16%	129	2.404	+0.16%	103	2.404	+0.16%	64
9.6	9.469	-1.36%	32	9.615	+0.16%	25	9.766	+1.73%	15
19.2	19.53	+1.73%	15	19.23	+0.16%	12	19.53	+1.73V	7
76.8	78.13	+1.73%	3	83.33	+8.51%	2	78.13	+1.73%	1
96	104.2	+8.51%	2	NA	—	—	NA	—	—
300	312.5	+4.17%	0	NA	—	—	NA	—	—
500	NA	—	—	NA	—	—	NA	—	—
HIGH	312.5	—	0	250	—	0	156.3	—	0
LOW	1.221	—	255	0.977	—	255	0.6104	—	255

BAUD RATE (K)	Fosc = 7.15909 MHz		SPBRG value (decimal)	5.0688 MHz		SPBRG value (decimal)	4 MHz		SPBRG value (decimal)
	KBAUD	ERROR		KBAUD	ERROR		KBAUD	ERROR	
0.3	NA	—	—	0.31	+3.13%	255	0.3005	-0.17%	207
1.2	1.203	+0.23%	92	1.2	0	65	1.202	+1.67%	51
2.4	2.380	-0.83%	46	2.4	0	32	2.404	+1.67%	25
9.6	9.322	-2.90%	11	9.9	+3.13%	7	NA	—	—
19.2	18.64	-2.90%	5	19.8	+3.13%	3	NA	—	—
76.8	NA	—	—	79.2	+3.13%	0	NA	—	—
96	NA	—	—	NA	—	—	NA	—	—
300	NA	—	—	NA	—	—	NA	—	—
500	NA	—	—	NA	—	—	NA	—	—
HIGH	111.9	—	0	79.2	—	0	62.500	—	0
LOW	0.437	—	255	0.3094	—	255	3.906	—	255

BAUD RATE (K)	Fosc = 3.579545 MHz		SPBRG value (decimal)	1 MHz		SPBRG value (decimal)	32.768 MHz		SPBRG value (decimal)
	KBAUD	ERROR		KBAUD	ERROR		KBAUD	ERROR	
0.3	0.301	+0.23%	185	0.300	+0.16%	51	0.256	-14.67%	1
1.2	1.190	-0.83%	46	1.202	+0.16%	12	NA	—	—
2.4	2.432	+1.32%	22	2.232	-6.99%	6	NA	—	—
9.6	9.322	-2.90%	5	NA	—	—	NA	—	—
19.2	18.64	-2.90%	2	NA	—	—	NA	—	—
76.8	NA	—	—	NA	—	—	NA	—	—
96	NA	—	—	NA	—	—	NA	—	—
300	NA	—	—	NA	—	—	NA	—	—
500	NA	—	—	NA	—	—	NA	—	—
HIGH	55.93	—	0	15.63	—	0	0.512	—	0
LOW	0.2185	—	255	0.0610	—	255	0.0020	—	255

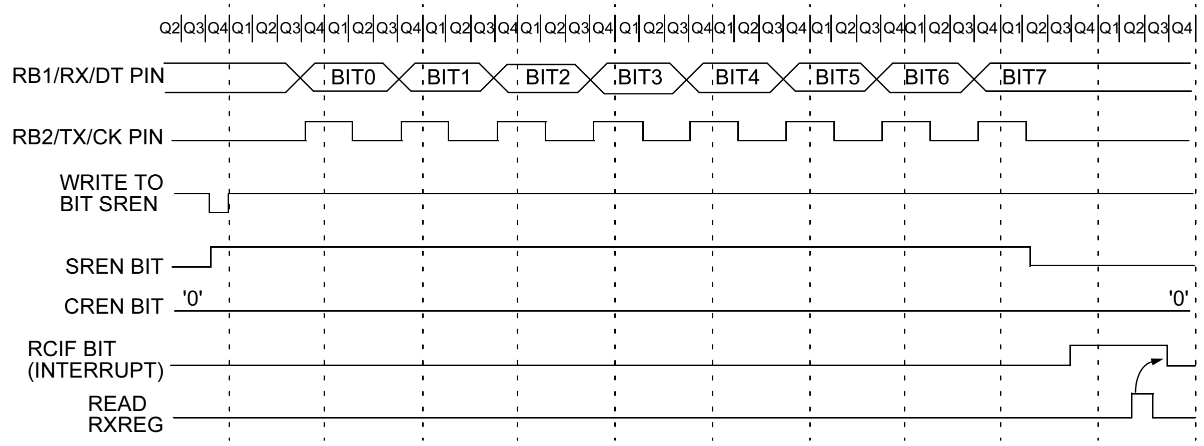
TABLE 12-5: BAUD RATES FOR ASYNCHRONOUS MODE (BRGH = 1)

BAUD RATE (K)	Fosc = 20 MHz		SPBRG value (decimal)	16 MHz		SPBRG value (decimal)	10 MHz		SPBRG value (decimal)
	KBAUD	ERROR		KBAUD	ERROR		KBAUD	ERROR	
9600	9.615	+0.16%	129	9.615	+0.16%	103	9.615	+0.16%	64
19200	19.230	+0.16%	64	19.230	+0.16%	51	18.939	-1.36%	32
38400	37.878	-1.36%	32	38.461	+0.16%	25	39.062	+1.7%	15
57600	56.818	-1.36%	21	58.823	+2.12%	16	56.818	-1.36%	10
115200	113.636	-1.36%	10	111.111	-3.55%	8	125	+8.51%	4
250000	250	0	4	250	0	3	NA	—	—
625000	625	0	1	NA	—	—	625	0	0
1250000	1250	0	0	NA	—	—	NA	—	—

BAUD RATE (K)	Fosc = 7.16 MHz		SPBRG value (decimal)	5.068 MHz		SPBRG value (decimal)	4 MHz		SPBRG value (decimal)
	KBAUD	ERROR		KBAUD	ERROR		KBAUD	ERROR	
9600	9.520	-0.83%	46	9598.485	0.016%	32	9615.385	0.160%	25
19200	19.454	+1.32%	22	18632.35	-2.956%	16	19230.77	0.160%	12
38400	37.286	-2.90%	11	39593.75	3.109%	7	35714.29	-6.994%	6
57600	55.930	-2.90%	7	52791.67	-8.348%	5	62500	8.507%	3
115200	111.860	-2.90%	3	105583.3	-8.348%	2	125000	8.507%	1
250000	NA	—	—	316750	26.700%	0	250000	0.000%	0
625000	NA	—	—	NA	—	—	NA	—	—
1250000	NA	—	—	NA	—	—	NA	—	—

BAUD RATE (K)	Fosc = 3.579 MHz		SPBRG value (decimal)	1 MHz		SPBRG value (decimal)	32.768 MHz		SPBRG value (decimal)
	KBAUD	ERROR		KBAUD	ERROR		KBAUD	ERROR	
9600	9725.543	1.308%	22	8.928	-6.994%	6	NA	NA	NA
19200	18640.63	-2.913%	11	20833.3	8.507%	2	NA	NA	NA
38400	37281.25	-2.913%	5	31250	-18.620%	1	NA	NA	NA
57600	55921.88	-2.913%	3	62500	+8.507	0	NA	NA	NA
115200	111243.8	-2.913%	1	NA	—	—	NA	NA	NA
250000	223687.5	-10.525%	0	NA	—	—	NA	NA	NA
625000	NA	—	—	NA	—	—	NA	NA	NA
1250000	NA	—	—	NA	—	—	NA	NA	NA

FIGURE 12-14: SYNCHRONOUS RECEPTION (MASTER MODE, SREN)



Note 1: Timing diagram demonstrates Sync Master mode with bit SREN = ‘1’ and bit BRG = ‘0’.

12.5 USART Synchronous Slave Mode

Synchronous Slave mode differs from the Master mode in the fact that the shift clock is supplied externally at the RB2/TX/CK pin (instead of being supplied internally in Master mode). This allows the device to transfer or receive data while in SLEEP mode. Slave mode is entered by clearing bit CSRC (TXSTA<7>).

12.5.1 USART SYNCHRONOUS SLAVE TRANSMIT

The operation of the Synchronous Master and Slave modes are identical except in the case of the SLEEP mode.

If two words are written to the TXREG and then the `SLEEP` instruction is executed, the following will occur:

a) The first word will immediately transfer to the TSR register and transmit.
b) The second word will remain in TXREG register.
c) Flag bit TXIF will not be set.
d) When the first word has been shifted out of TSR, the TXREG register will transfer the second word to the TSR and flag bit TXIF will now be set.
e) If enable bit TXIE is set, the interrupt will wake the chip from SLEEP and if the global interrupt is enabled, the program will branch to the interrupt vector (0004h).

Steps to follow when setting up a Synchronous Slave Transmission:

1. Enable the synchronous slave serial port by setting bits SYNC and SPEN and clearing bit CSRC.
2. Clear bits CREN and SREN.
3. If interrupts are desired, then set enable bit TXIE.
4. If 9-bit transmission is desired, then set bit TX9.
5. Enable the transmission by setting enable bit TXEN.
6. If 9-bit transmission is selected, the ninth bit should be loaded in bit TX9D.
7. Start transmission by loading data to the TXREG register.

REGISTER 14-1: CONFIGURATION WORD

CP1	CP0	CP1	CP0	—	CPD	LVP	BODEN	MCLRE	FOSC2	$\overline{\text{PWRTE}}$	WDTE	F0SC1	F0SC0

bit 13 bit 0

bit 13-10: **CP1:CP0:** Code Protection bits (2)
Code protection for 2K program memory
`11` = Program memory code protection off
`10` = 0400h-07FFh code protected
`01` = 0200h-07FFh code protected
`00` = 0000h-07FFhcode protected

Code protection for 1K program memory
`11` = Program memory code protection off
`10` = Program memory code protection off
`01` = 0200h-03FFh code protected
`00` = 0000h-03FFh code protected

bit 9: **Unimplemented**: Read as ‘0’

bit 8: **CPD:** Data Code Protection bit(3)
`1` = Data memory code protection off
`0` = Data memory code protected

bit 7: **LVP**: Low Voltage Programming Enable
`1` = RB4/PGM pin has PGM function, low voltage programming enabled
`0` = RB4/PGM is digital I/O, HV on $\overline{\text{MCLR}}$ must be used for programming

bit 6: **BODEN**: Brown-out Detect Reset Enable bit (1)
`1` = BOD Reset enabled
`0` = BOD Reset disabled

bit 5: **MCLRE**: RA5/$\overline{\text{MCLR}}$ pin function select
`1` = RA5/$\overline{\text{MCLR}}$ pin function is $\overline{\text{MCLR}}$
`0` = RA5/$\overline{\text{MCLR}}$ pin function is digital Input, $\overline{\text{MCLR}}$ internally tied to VDD

bit 3: **$\overline{\text{PWRTEN}}$**: Power-up Timer Enable bit (1)
`1` = PWRT disabled
`0` = PWRT enabled

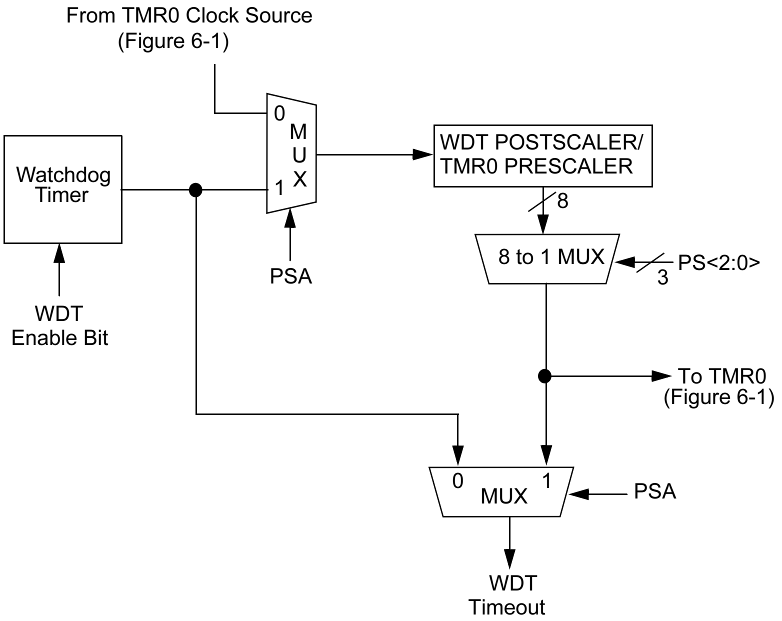
bit 2: **WDTEN**: Watchdog Timer Enable bit
`1` = WDT enabled
`0` = WDT disabled

bit 4, 1-0: **FOSC2:FOSC0**: Oscillator Selection bits(4)
`111` = ER oscillator: CLKOUT function on RA6/OSC2/CLKOUT pin, Resistor on RA7/OSC1/CLKIN
`110` = ER oscillator: I/O function on RA6/OSC2/CLKOUT pin, Resistor on RA7/OSC1/CLKIN
`101` = INTRC oscillator: CLKOUT function on RA6/OSC2/CLKOUT pin, I/O function on RA7/OSC1/CLKIN
`100` = INTRC oscillator: I/O function on RA6/OSC2/CLKOUT pin, I/O function on RA7/OSC1/CLKIN
`011` = EC: I/O function on RA6/OSC2/CLKOUT pin, CLKIN on RA7/OSC1/CLKIN
`010` = HS oscillator: High speed crystal/resonator on RA6/OSC2/CLKOUT and RA7/OSC1/CLKIN
`001` = XT oscillator: Crystal/resonator on RA6/OSC2/CLKOUT and RA7/OSC1/CLKIN
`000` = LP oscillator: Low power crystal on RA6/OSC2/CLKOUT and RA7/OSC1/CLKIN

Note
1: Enabling Brown-out Detect Reset automatically enables Power-up Timer (PWRT) regardless of the value of bit $\overline{\text{PWRTE}}$. Ensure the Power-up Timer is enabled anytime Brown-out Detect Reset is enabled.
2: All of the CP1:CP0 pairs have to be given the same value to enable the code protection scheme listed.
3: The entire data EEPROM will be erased when the code protection is turned off.
4: When $\overline{\text{MCLR}}$ is asserted in INTRC or ER mode, the internal clock oscillator is disabled.

Legend			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	1 = bit is set	0 = bit is cleared	x = bit is unknown

FIGURE 14-16: WATCHDOG TIMER BLOCK DIAGRAM



Note 1: T0SE, T0CS, PSA, PS0-PS2 are bits in the OPTION register.

TABLE 14-10: SUMMARY OF WATCHDOG TIMER REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR Reset	Value on all other RESETS
2007h	Config. bits	LVP	BODEN	MCLRE	FOSC2	$\overline{\text{PWRTE}}$	WDTE	FOSC1	FOSC0	uuuu uuuu	uuuu uuuu
81h	OPTION	$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111

Legend: – = Unimplemented location, read as “0”, + = Reserved for future use
Note 1: Shaded cells are not used by the Watchdog Timer.

14.9 Power-Down Mode (SLEEP)

The Power-down mode is entered by executing a `SLEEP` instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the $\overline{\text{PD}}$ bit in the STATUS register is cleared, the $\overline{\text{TO}}$ bit is set, and the oscillator driver is turned off. The I/O ports maintain the status they had, before `SLEEP` was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, all I/O pins should be either at V_{DD}, or V_{SS}, with no external circuitry drawing current from the I/O pin and the comparators, and V_{REF} should be disabled. I/O pins that are hi-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The T0CKI input should also be at V_{DD} or V_{SS} for lowest current consumption. The contribution from on-chip pull-ups on PORTB should be considered.

The $\overline{\text{MCLR}}$ pin must be at a logic high level (V_{IHMC}).

Note:	It should be noted that a RESET generated by a WDT timeout does not drive $\overline{\text{MCLR}}$ pin low.

14.9.1 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

1. External RESET input on $\overline{\text{MCLR}}$ pin
2. Watchdog Timer Wake-up (if WDT was enabled)
3. Interrupt from RB0/INT pin, RB Port change, or the Peripheral Interrupt (Comparator).

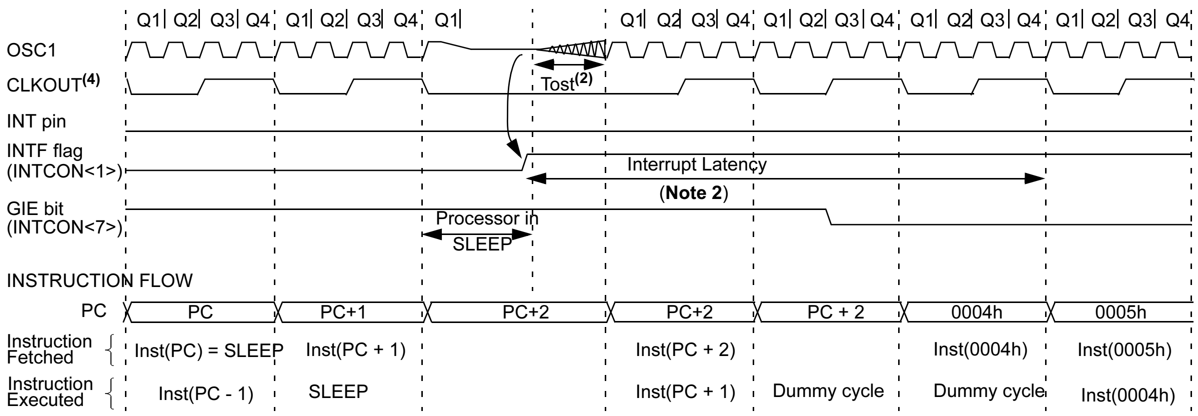
The first event will cause a device RESET. The two latter events are considered a continuation of program execution. The $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits in the STATUS register can be used to determine the cause of device RESET. $\overline{\text{PD}}$ bit, which is set on power-up is cleared when SLEEP is invoked. $\overline{\text{TO}}$ bit is cleared if WDT Wake-up occurred.

When the `SLEEP` instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the `SLEEP` instruction. If the GIE bit is set (enabled), the device executes the instruction after the `SLEEP` instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following `SLEEP` is not desirable, the user should have an `NOP` after the `SLEEP` instruction.

Note:	If the global interrupts are disabled (GIE is cleared), but any interrupt source has both its interrupt enable bit and the corresponding interrupt flag bits set, the device will immediately wake-up from SLEEP. The `SLEEP` instruction is completely executed.

The WDT is cleared when the device wakes-up from SLEEP, regardless of the source of wake-up.

FIGURE 14-17: WAKE-UP FROM SLEEP THROUGH INTERRUPT



Note 1: XT, HS or LP Oscillator mode assumed.

2: TOST = 1024TOSC (drawing not to scale). Approximately 1 μs delay will be there for ER Osc mode.

3: GIE = '1' assumed. In this case after wake- up, the processor jumps to the interrupt routine. If GIE = '0', execution will continue in-line.

4: CLKOUT is not available in these Osc modes, but shown here for timing reference.

14.10 Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

Note:	The entire data EEPROM and FLASH program memory will be erased when the code protection is turned off. The INTRC calibration data is not erased.

14.11 User ID Locations

Four memory locations (2000h-2003h) are designated as user ID locations where the user can store checksum or other code-identification numbers. These locations are not accessible during normal execution but are readable and writable during program/verify. Only the Least Significant 4 bits of the user ID locations are used.

RETLW Return with Literal in W

Syntax:	[*label*] RETLW k
Operands:	0 ≤ k ≤ 255
Operation:	k → (W); TOS → PC
Status Affected:	None
Encoding:	`11` `01xx` `kkkk` `kkkk`
Description:	The W register is loaded with the eight bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a two-cycle instruction.
Words:	1
Cycles:	2

Example

```
        CALL TABLE;W contains table
                  ;offset value
        •         ;W now has table
        value
TABLE   •
        •
        ADDWF PC  ;W = offset
        RETLW k1  ;Begin table
        RETLW k2  ;
        •
        •
        •
        RETLW kn  ; End of table
```

Before Instruction
W = 0x07
After Instruction
W = value of k8

RETURN Return from Subroutine

Syntax:	[*label*] RETURN
Operands:	None
Operation:	TOS → PC
Status Affected:	None
Encoding:	`00` `0000` `0000` `1000`
Description:	Return from subroutine. The stack is POPed and the top of the stack (TOS) is loaded into the program counter. This is a two-cycle instruction.
Words:	1
Cycles:	2

Example

```
RETURN
```

After Interrupt
PC = TOS

RLF Rotate Left f through Carry

Syntax:	[*label*] RLF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	See description below
Status Affected:	C
Encoding:	`00` `1101` `dfff` `ffff`
Description:	The contents of register 'f' are rotated one bit to the left through the Carry Flag. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words:	1
Cycles:	1

Example

```
RLF     REG1, 0
```

Before Instruction
REG1 = 1110 0110
C = 0
After Instruction
REG1 = 1110 0110
W = 1100 1100
C = 1

XORLW	**Exclusive OR Literal with W**
Syntax:	[*label*] XORLW k
Operands:	$0 \le k \le 255$
Operation:	(W) .XOR. k → (W)
Status Affected:	Z
Encoding:	`11` `1010` `kkkk` `kkkk`
Description:	The contents of the W register are XOR'ed with the eight bit literal 'k'. The result is placed in the W register.
Words:	1
Cycles:	1
Example:	`XORLW 0xAF` Before Instruction W = 0xB5 After Instruction W = 0x1A

XORWF	**Exclusive OR W with f**
Syntax:	[*label*] XORWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(W) .XOR. (f) → (dest)
Status Affected:	Z
Encoding:	`00` `0110` `dfff` `ffff`
Description:	Exclusive OR the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.
Words:	1
Cycles:	1
Example	`XORWF REG1, 1` Before Instruction REG1 = 0xAF W = 0xB5 After Instruction REG1 = 0x1A W = 0xB5

17.0 ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings†

Ambient temperature under bias	-40 to +125°C
Storage temperature	-65°C to +150°C
Voltage on VDD with respect to VSS	-0.3 to +6.5V
Voltage on $\overline{\text{MCLR}}$ and RA4 with respect to VSS	-0.3 to +14V
Voltage on all other pins with respect to VSS	-0.3V to VDD + 0.3V
Total power dissipation(1)	800 mW
Maximum current out of VSS pin	300 mA
Maximum current into VDD pin	250 mA
Input clamp current, IIK (VI < 0 or VI > VDD)	± 20 mA
Output clamp current, IOK (Vo < 0 or Vo >VDD)	± 20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by PORTA and PORTB	200 mA
Maximum current sourced by PORTA and PORTB	200 mA

Note 1: Power dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD}-V_{OH}) \times I_{OH}\} + \sum(V_{Ol} \times I_{OL})$

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Note: Voltage spikes below VSS at the $\overline{\text{MCLR}}$ pin, inducing currents greater than 80 mA, may cause latchup. Thus, a series resistor of 50-100 Ω should be used when applying a “low” level to the $\overline{\text{MCLR}}$ pin rather than pulling this pin directly to VSS

17.2 DC Characteristics: PIC16F62X (Commercial, Industrial, Extended)
PIC16LF62X (Commercial, Industrial)

DC CHARACTERISTICS	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for industrial and 0°C ≤ T_A ≤ +70°C for commercial and -40°C ≤ T_A ≤ +125°C for extended Operating voltage V_{DD} range as described in DC spec Table 17-1 and Table 17-2

Param. No.	Sym	Characteristic/Device	Min	Typ†	Max	Unit	Conditions
	V_{IL}	**Input Low Voltage**					
		I/O ports					
D030		with TTL buffer	V_{SS}	—	0.8	V	V_{DD} = 4.5V to 5.5V
					0.15 V_{DD}	V	otherwise
D031		with Schmitt Trigger input	V_{SS}		0.2 V_{DD}	V	
D032		$\overline{MCLR}$, RA4/T0CKI,OSC1 (in ER mode)	V_{SS}	—	0.2 V_{DD}	V	**(Note1)**
D033		OSC1 (in XT and HS)	V_{SS}	—	0.3 V_{DD}	V	
		OSC1 (in LP)	V_{SS}	—	0.6 V_{DD} - 1.0	V	
	V_{IH}	**Input High Voltage**					
		I/O ports					
D040		with TTL buffer	2.0V	—	V_{DD}	V	V_{DD} = 4.5V to 5.5V
			.25 V_{DD} + 0.8V		V_{DD}	V	otherwise
D041		with Schmitt Trigger input	0.8 V_{DD}	—	V_{DD}	V	
D042		$\overline{MCLR}$ RA4/T0CKI	0.8 V_{DD}	—	V_{DD}	V	
D043		OSC1 (XT, HS and LP)	0.7 V_{DD}	—	V_{DD}	V	
D043A		OSC1 (in ER mode)	0.9 V_{DD}			V	**(Note1)**
D070	I_{PURB}	**PORTB weak pull-up current**	50	200	400	μA	V_{DD} = 5.0V, V_{PIN} = V_{SS}
	I_{IL}	**Input Leakage Current**$^{(2), (3)}$					
		I/O ports (Except PORTA)			±1.0	μA	$V_{SS} \le V_{PIN} \le V_{DD}$, pin at hi-impedance
D060		PORTA	—	—	±0.5	μA	$V_{SS} \le V_{PIN} \le V_{DD}$, pin at hi-impedance
D061		RA4/T0CKI	—	—	±1.0	μA	$V_{SS} \le V_{PIN} \le V_{DD}$
D063		OSC1, $\overline{MCLR}$	—	—	±5.0	μA	$V_{SS} \le V_{PIN} \le V_{DD}$, XT, HS and LP osc configuration
	V_{OL}	**Output Low Voltage**					
D080		I/O ports	—	—	0.6	V	I_{OL}=8.5 mA, V_{DD}=4.5V, -40° to +85°C
			—	—	0.6	V	I_{OL}=7.0 mA, V_{DD}=4.5V, +125°C
D083		OSC2/CLKOUT (ER only)	—	—	0.6	V	I_{OL}=1.6 mA, V_{DD}=4.5V, -40° to +85°C
			—	—	0.6	V	I_{OL}=1.2 mA, V_{DD}=4.5V, +125°C
	V_{OH}	**Output High Voltage**$^{(3)}$					
D090		I/O ports (Except RA4)	V_{DD} - 0.7	—	—	V	I_{OH}=-3.0 mA, V_{DD}=4.5V, -40° to +85°C
			V_{DD} - 0.7	—	—	V	I_{OH}=-2.5 mA, V_{DD}=4.5V, +125°C
D092		OSC2/CLKOUT (ER only)	V_{DD} - 0.7	—	—	V	I_{OH}=-1.3 mA, V_{DD}=4.5V, -40° to +85°C
			V_{DD} - 0.7	—	—	V	I_{OH}=-1.0 mA, V_{DD}=4.5V, +125°C
D150	V_{OD}	**Open-Drain High Voltage**		—	8.5	V	RA4 pin PIC16F62X, PIC16LF62X*
		Capacitive Loading Specs on Output Pins					
D100*	C_{OSC2}	OSC2 pin		—	15	pF	In XT, HS and LP modes when external clock used to drive OSC1.
D101*	C_{IO}	All I/O pins/OSC2 (in ER mode)		—	50	pF	

* These parameters are characterized but not tested.

† Data in “Typ” column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In ER oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC16F62X be driven with external clock in ER mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

TABLE 17-4: EXTERNAL CLOCK TIMING REQUIREMENTS

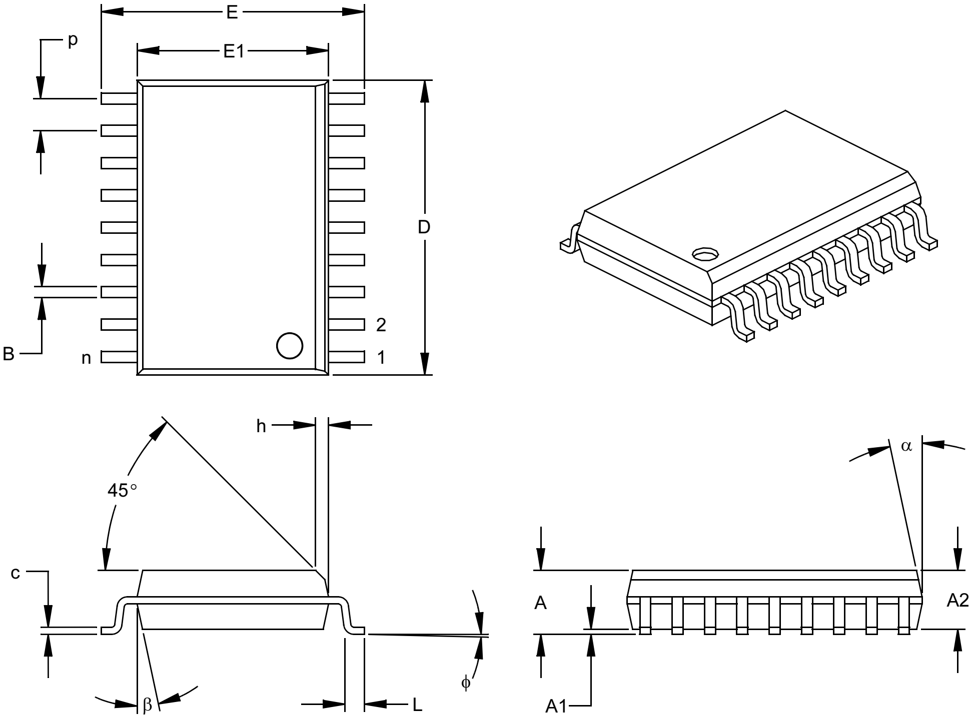
Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	Fosc	External CLKIN Frequency(1)	DC	—	4	MHz	XT and ER Osc mode, VDD = 5.0V
			DC	—	20	MHz	HS Osc mode
			DC	—	200	kHz	LP Osc mode
		Oscillator Frequency(1)		—	4	MHz	ER Osc mode, VDD = 5.0V
			0.1	—	4	MHz	XT Osc mode
			1	—	20	MHz	HS Osc mode
				—	200	kHz	LP Osc mode
			3.65	4	4.28	MHz	INTRC mode (fast), VDD = 5.0V
				37		kHz	INTRC mode (slow)
4	INTRC	Internal Calibrated RC	3.65	4.00	4.28	MHz	VDD = 5.0V
5	ER	External Biased ER Frequency	10 kHz		8 MHz		VDD = 5.0V
1	Tosc	External CLKIN Period(1)	250	—	—	ns	XT and ER Osc mode
			50	—	—	ns	HS Osc mode
			5	—	—	µs	LP Osc mode
		Oscillator Period(1)	250	—	—	ns	ER Osc mode
			250	—	10,000	ns	XT Osc mode
			50	—	1,000	ns	HS Osc mode
			5			µs	LP Osc mode
				250		ns	INTRC mode (fast)
				27		µs	INTRC mode (slow)
2	Tcy	Instruction Cycle Time	1.0	TCY	DC	ns	TCY = 4/FOSC
3	TosL, TosH	External CLKIN (OSC1) High External CLKIN Low	100 *	—	—	ns	XT oscillator, TOSC L/H duty cycle*

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (Tcy) equals four times the input oscillator time-based period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "Min." values with an external clock applied to the OSC1 pin. When an external clock input is used, the "Max" cycle time limit is "DC" (no clock) for all devices.

K04-051 18-Lead Plastic Small Outline (SO) – Wide, 300 mil



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.446	.454	.462	11.33	11.53	11.73
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.012	0.23	0.27	0.30
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-013
Drawing No. C04-051